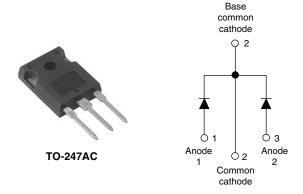


www.vishay.com

Vishay Semiconductors

Ultrafast Rectifier, 2 x 40 A FRED Pt®



| PRODUCT SUMMARY | | | | | |
|----------------------------------|----------------|--|--|--|--|
| Package | TO-247AC | | | | |
| I _{F(AV)} | 2 x 40 A | | | | |
| V_{R} | 200 V | | | | |
| V _F at I _F | 0.8 V | | | | |
| t _{rr} typ. | 34 ns | | | | |
| T _J max. | 175 °C | | | | |
| Diode variation | Common cathode | | | | |

FEATURES

- · Ultrafast recovery time
- Low forward voltage drop
- Low leakage current
- 175 °C operating junction temperature
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912





ROHS COMPLIANT HALOGEN FREE

DESCRIPTIONS / APPLICATIONS

VS-80CPU02... series are the state of the art ultrafast recovery rectifiers designed with optimized performance of forward voltage drop and ultrafast recovery time.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in the output rectification stage of welding, SMPS, UPS, DC/DC converters as well as freewheeling diodes in low voltage inverters and chopper motor drives.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

| ABSOLUTE MAXIMUM RATINGS | | | | | | |
|---|-----------------------------------|-------------------------|-------------|-------|--|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MAX. | UNITS | | |
| Repetitive peak reverse voltage | V_{RRM} | | 200 | V | | |
| Average rectified forward current per leg | $I_{F(AV)}$ | T _C = 145 °C | 40 | | | |
| total device | | | 80 | Α | | |
| Non-repetitive peak surge current per leg | I _{FSM} | T _J = 25 °C | 330 | | | |
| Operating junction and storage temperatures | T _J , T _{Stg} | | -65 to +175 | °C | | |

| ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|--|-------------------------------------|--|------|------|------|-------|--|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS | |
| Breakdown voltage, blocking voltage | V _{BR} , V _R | I _R = 100 μA | 200 | - | - | | |
| | | I _F = 40 A | - | 0.94 | 1.02 | | |
| Forward voltage | V _F | I _F = 40 A, T _J = 150 °C | - | 0.80 | 0.90 | V | |
| Forward voltage | | I _F = 80 A | - | 1.07 | 1.20 | | |
| | | I _F = 80 A, T _J = 150 °C | - | 0.97 | 1.08 | | |
| Doverno lockogo overent | | $V_R = V_R$ rated | - | - | 5 | | |
| Reverse leakage current | | T _J = 150 °C, V _R = V _R rated | - | - | 500 | μA | |
| Junction capacitance | C _T | V _R = 200 V | - | 120 | - | pF | |
| Series inductance | L _S | Measured lead to lead 5 mm from package body | - | 3.5 | - | nH | |



VS-80CPU02-F3, VS-80CPU02-N3

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| DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified) | | | | | | | |
|---|------------------|--|---|------|------|-------|----|
| PARAMETER | SYMBOL | TEST C | MIN. | TYP. | MAX. | UNITS | |
| | | $I_F = 1.0 \text{ A}, dI_F/dt = 0.0 \text{ A}$ | $I_F = 1.0 \text{ A}, dI_F/dt = 100 \text{ A/}\mu\text{s}, V_R = 30 \text{ V}$ | | 34 | - | |
| Reverse recovery time | t _{rr} | T _J = 25 °C | $I_F = 40 \text{ A}$ $dI_F/dt = -200 \text{ A/}\mu\text{s}$ $V_R = 200 \text{ V}$ | - | 33 | - | ns |
| | | T _J = 125 °C | | - | 54 | - | |
| Dools recovery oversent | I _{RRM} | T _J = 25 °C | | - | 3.4 | - | Α |
| Peak recovery current | | T _J = 125 °C | | - | 8 | - | |
| Reverse recovery charge | Q _{rr} | T _J = 25 °C | | - | 56 | - | nC |
| | | T _J = 125 °C | | - | 216 | - | |

| THERMAL - MECHANICAL | SPECIFICA | ATIONS | | | | |
|---|-----------------------------------|--|--------------|------|------------|------------------------|
| PARAMETER | SYMBOL | TEST CONDITIONS | MIN. | TYP. | MAX. | UNITS |
| Maximum junction and storage temperature range | T _J , T _{Stg} | | -65 | - | 175 | °C |
| Thermal resistance, junction to case per leg | R _{thJC} | | - | 0.46 | 0.70 | |
| Thermal resistance, junction to ambient per leg | R _{thJA} | Typical socket mount | - | - | 40 | °C/W |
| Thermal resistance, case to heatsink | R _{thCS} | Mounting surface, flat, smooth and greased | - | 0.3 | - | |
| Weight | | | - | 6.0 | - | g |
| Weight | | | - | 0.21 | - | oz. |
| Mounting torque | | | 6.0 (5.0) | - | 12 (10) | kgf · cm (lbf · in) |
| Marking device | | Case style TO-247AC | 80CPU02 | | | |



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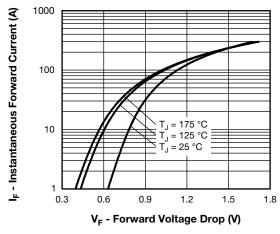


Fig. 1 - Typical Forward Voltage Drop Characteristics

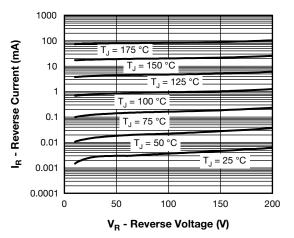


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

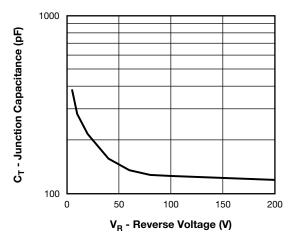


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

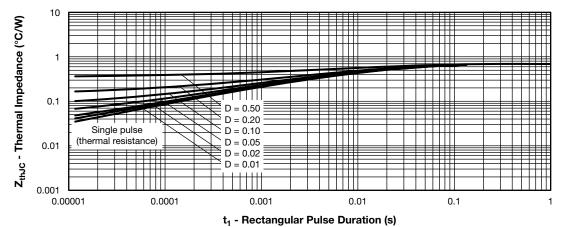


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



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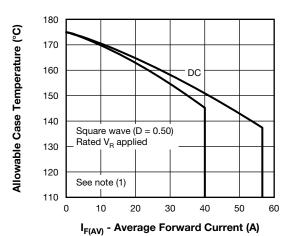


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

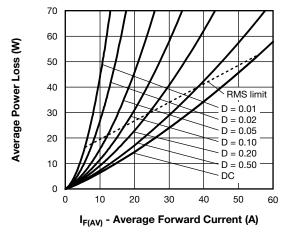


Fig. 6 - Forward Power Loss Characteristics

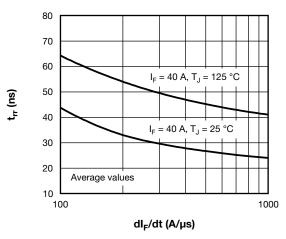


Fig. 7 - Typical Reverse Recovery Time vs. $dI_{\mbox{\scriptsize F}}/dt$

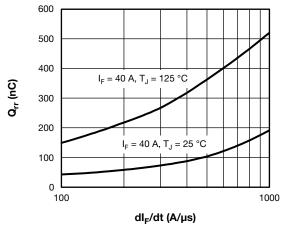


Fig. 8 - Typical Stored Charge vs. dl_F/dt

Note

 $\begin{array}{l} \text{(1)} \ \ \text{Formula used:} \ T_C = T_J - (Pd + Pd_{REV}) \times R_{th,JC}; \\ Pd = \text{Forward power loss} = I_{F(AV)} \times V_{FM} \ \text{at } (I_{F(AV)}/D) \ \text{(see fig. 6)}; \\ Pd_{REV} = \text{Inverse power loss} = V_{R1} \times I_R \ \text{(1 - D)}; \ I_R \ \text{at } V_{R1} = \text{Rated } V_R \\ \end{array}$

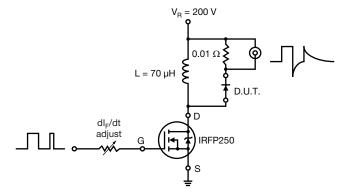
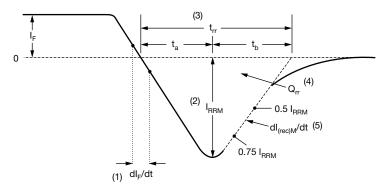


Fig. 9 - Reverse Recovery Parameter Test Circuit

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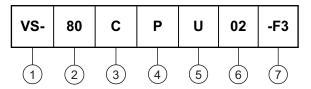


- (1) dl_F/dt rate of change of current through zero crossing
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}
- (2) I_{RRM} peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3) $t_{\rm rr}$ reverse recovery time measured from zero crossing point of negative going $I_{\rm F}$ to point where a line passing through 0.75 $I_{\rm RRM}$ and 0.50 $I_{\rm RRM}$ extrapolated to zero current.
- (5) $dI_{(rec)M}/dt$ peak rate of change of current during $t_{\rm b}$ portion of $t_{\rm rr}$

Fig. 10 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



- 1 Vishay Semiconductors product
- 2 Current rating (80 = 80 A)
- 3 Circuit configuration:

C = common cathode

- 4 P = TO-247AC
- 5 U = ultrafast rectifier
- 6 Voltage rating (02 = 200 V)
- 7 Environmental digit:
 - -F3 = RoHS-compliant and totally lead (Pb)-free
 - -N3 = halogen-free, RoHS-compliant and totally lead (Pb)-free

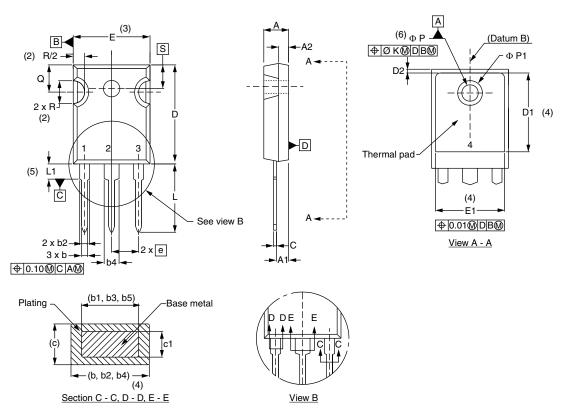
| ORDERING INFORMATION (Example) | | | | | | | |
|--------------------------------|-------------------|------------------------|-------------------------|--|--|--|--|
| PREFERRED P/N | QUANTITY PER TUBE | MINIMUM ORDER QUANTITY | PACKAGING DESCRIPTION | | | | |
| VS-80CPU02-F3 | 25 | 500 | Antistatic plastic tube | | | | |
| VS-80CPU02-N3 | 25 | 500 | Antistatic plastic tube | | | | |

| LINKS TO RELATED DOCUMENTS | | | | | |
|----------------------------|--------------------------|--|--|--|--|
| Dimensions | www.vishay.com/doc?95542 | | | | |
| Part marking | www.vishay.com/doc?95007 | | | | |
| SPICE model | www.vishay.com/doc?96096 | | | | |

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TO-247AC - 50 mils L/F

DIMENSIONS in millimeters and inches



| MILLIMETERS | | INCHES | | NOTES |
|-------------|---|---|--|---|
| MIN. | MAX. | MIN. | MAX. | NOTES |
| 4.65 | 5.31 | 0.183 | 0.209 | |
| 2.21 | 2.59 | 0.087 | 0.102 | |
| 1.17 | 1.37 | 0.046 | 0.054 | |
| 0.99 | 1.40 | 0.039 | 0.055 | |
| 0.99 | 1.35 | 0.039 | 0.053 | |
| 1.65 | 2.39 | 0.065 | 0.094 | |
| 1.65 | 2.34 | 0.065 | 0.092 | |
| 2.59 | 3.43 | 0.102 | 0.135 | |
| 2.59 | 3.38 | 0.102 | 0.133 | |
| 0.38 | 0.89 | 0.015 | 0.035 | |
| 0.38 | 0.84 | 0.015 | 0.033 | |
| 19.71 | 20.70 | 0.776 | 0.815 | 3 |
| 13.08 | - | 0.515 | - | 4 |
| | MIN. 4.65 2.21 1.17 0.99 0.99 1.65 1.65 2.59 2.59 0.38 0.38 19.71 | MIN. MAX. 4.65 5.31 2.21 2.59 1.17 1.37 0.99 1.40 0.99 1.35 1.65 2.39 1.65 2.34 2.59 3.43 2.59 3.38 0.38 0.89 0.38 0.84 19.71 20.70 | MIN. MAX. MIN. 4.65 5.31 0.183 2.21 2.59 0.087 1.17 1.37 0.046 0.99 1.40 0.039 0.99 1.35 0.039 1.65 2.39 0.065 1.65 2.34 0.065 2.59 3.43 0.102 2.59 3.38 0.102 0.38 0.89 0.015 0.38 0.84 0.015 19.71 20.70 0.776 | MIN. MAX. MIN. MAX. 4.65 5.31 0.183 0.209 2.21 2.59 0.087 0.102 1.17 1.37 0.046 0.054 0.99 1.40 0.039 0.055 0.99 1.35 0.039 0.053 1.65 2.39 0.065 0.094 1.65 2.34 0.065 0.092 2.59 3.43 0.102 0.135 2.59 3.38 0.102 0.133 0.38 0.89 0.015 0.035 0.38 0.84 0.015 0.033 19.71 20.70 0.776 0.815 |

| SYMBOL | MILLIN | IETERS | INCHES | | NOTES |
|---------|----------|--------|--------|-------|-------|
| STWIBOL | MIN. | MAX. | MIN. | MAX. | NOTES |
| D2 | 0.51 | 1.35 | 0.020 | 0.053 | |
| Ш | 15.29 | 15.87 | 0.602 | 0.625 | 3 |
| E1 | 13.46 | - | 0.53 | - | |
| е | 5.46 | BSC | 0.215 | BSC | |
| ØK | 0.2 | 254 | 0.0 |)10 | |
| L | 14.20 | 16.10 | 0.559 | 0.634 | |
| L1 | 3.71 | 4.29 | 0.146 | 0.169 | |
| ØΡ | 3.56 | 3.66 | 0.14 | 0.144 | |
| Ø P1 | - | 7.39 | - | 0.291 | |
| Q | 5.31 | 5.69 | 0.209 | 0.224 | |
| R | 4.52 | 5.49 | 0.178 | 0.216 | |
| S | 5.51 BSC | | 0.217 | BSC | |
| | | | | | |

Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension c and Q

Revision: 20-Apr-17 **1** Document Number: 95542

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